



SOT1092-6(DD)

HVQFN36, plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 36 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

11 July 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-05-2018
Manufacturer package code	98ASA01250D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	36	-	



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2 Package outline

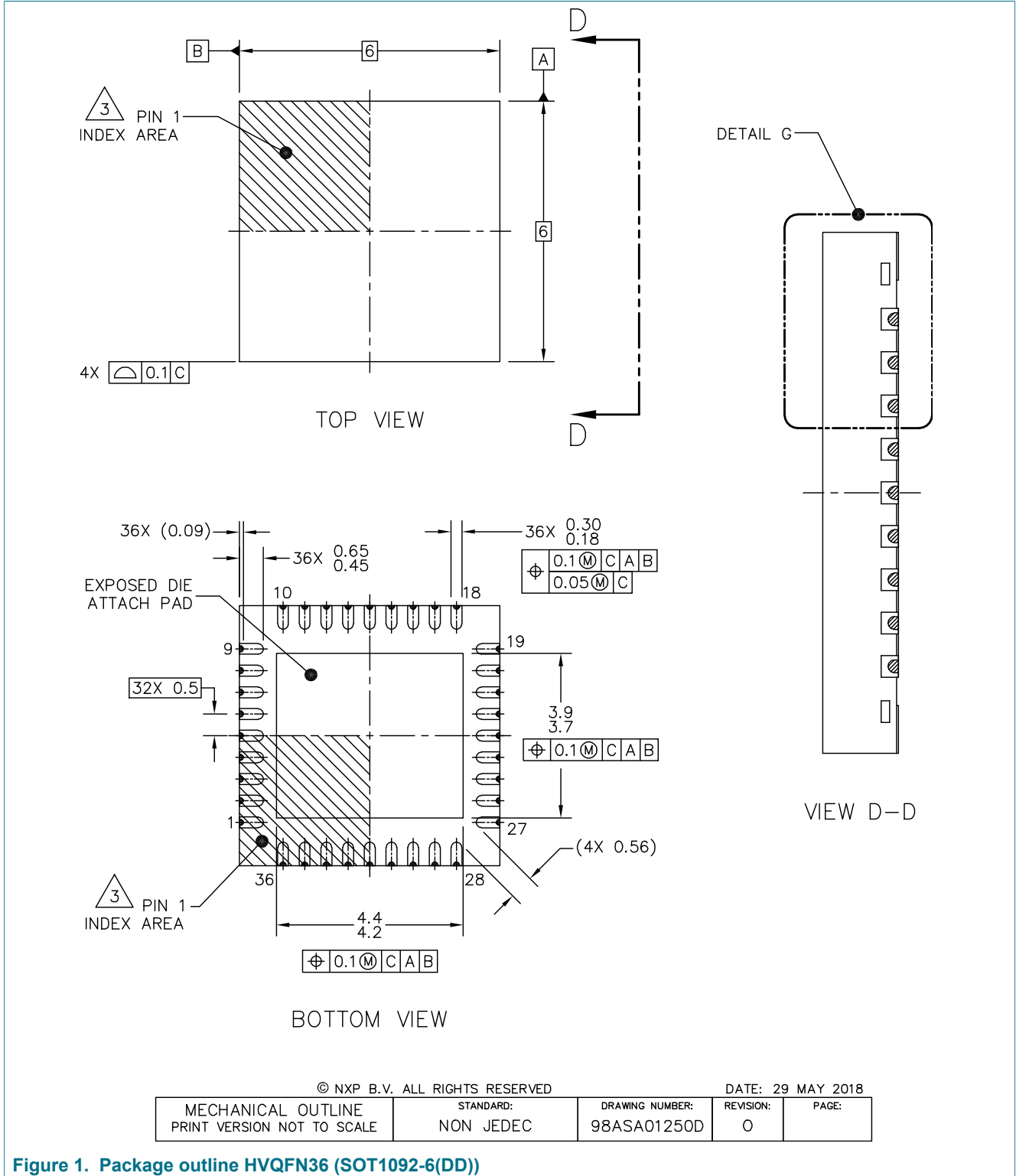


Figure 1. Package outline HVQFN36 (SOT1092-6(DD))

HVQFN36, plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 36 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

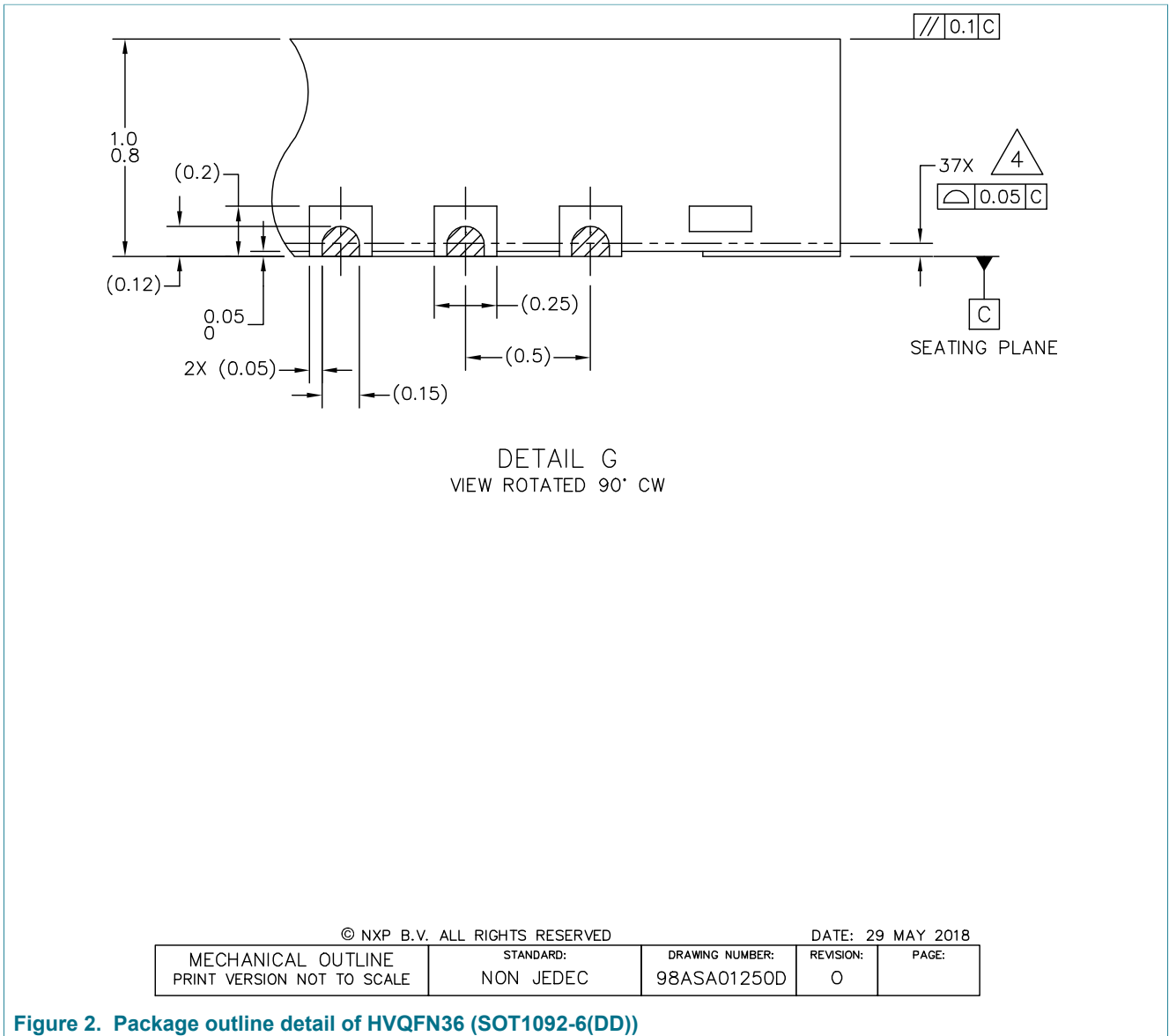


Figure 2. Package outline detail of HVQFN36 (SOT1092-6(DD))

HVQFN36, plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 36 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

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DATE: 29 MAY 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01250D	REVISION: 0	PAGE:
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Figure 3. Package outline note of HVQFN36 (SOT1092-6(DD))

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3 Soldering

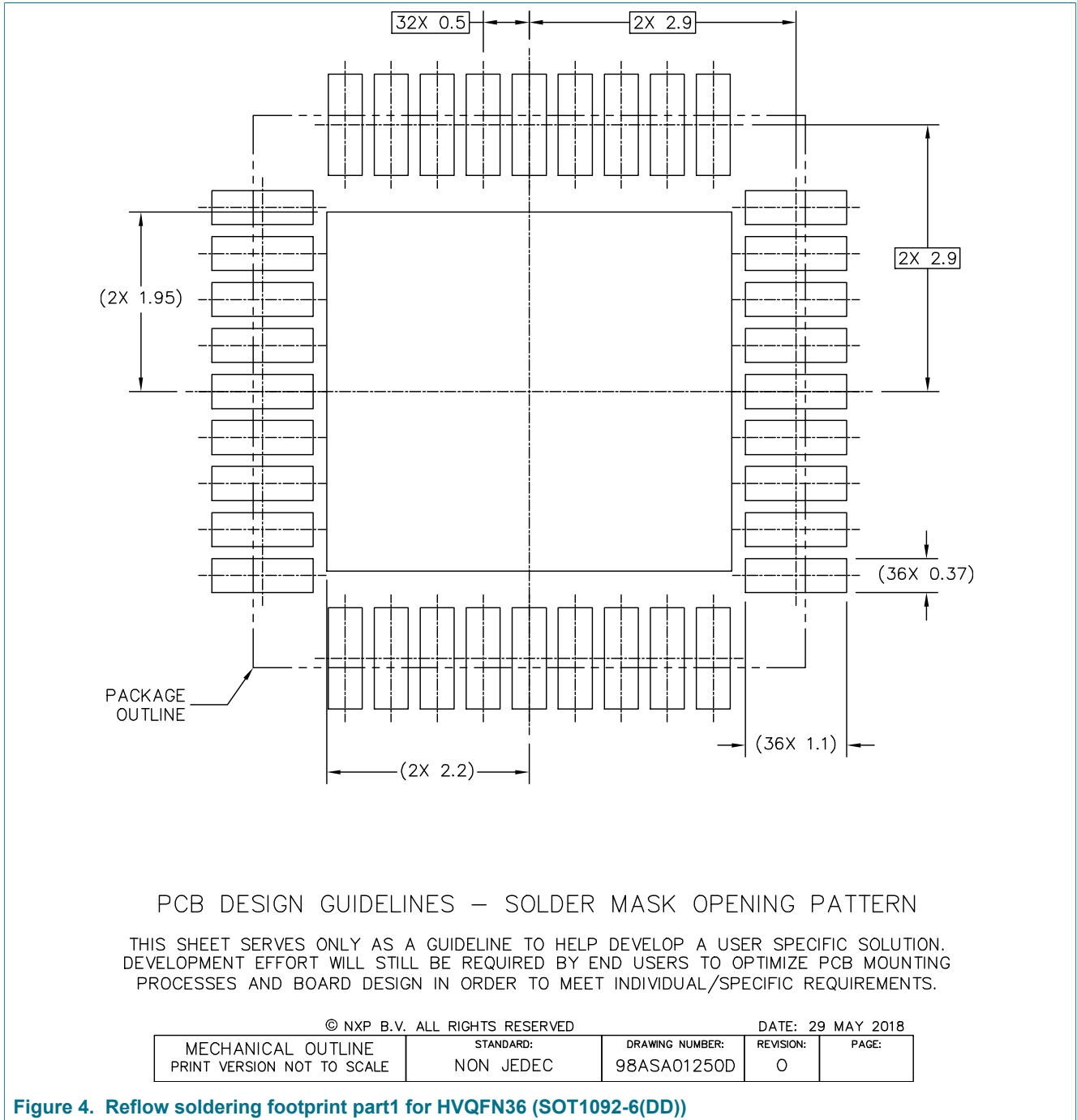


Figure 4. Reflow soldering footprint part1 for HVQFN36 (SOT1092-6(DD))

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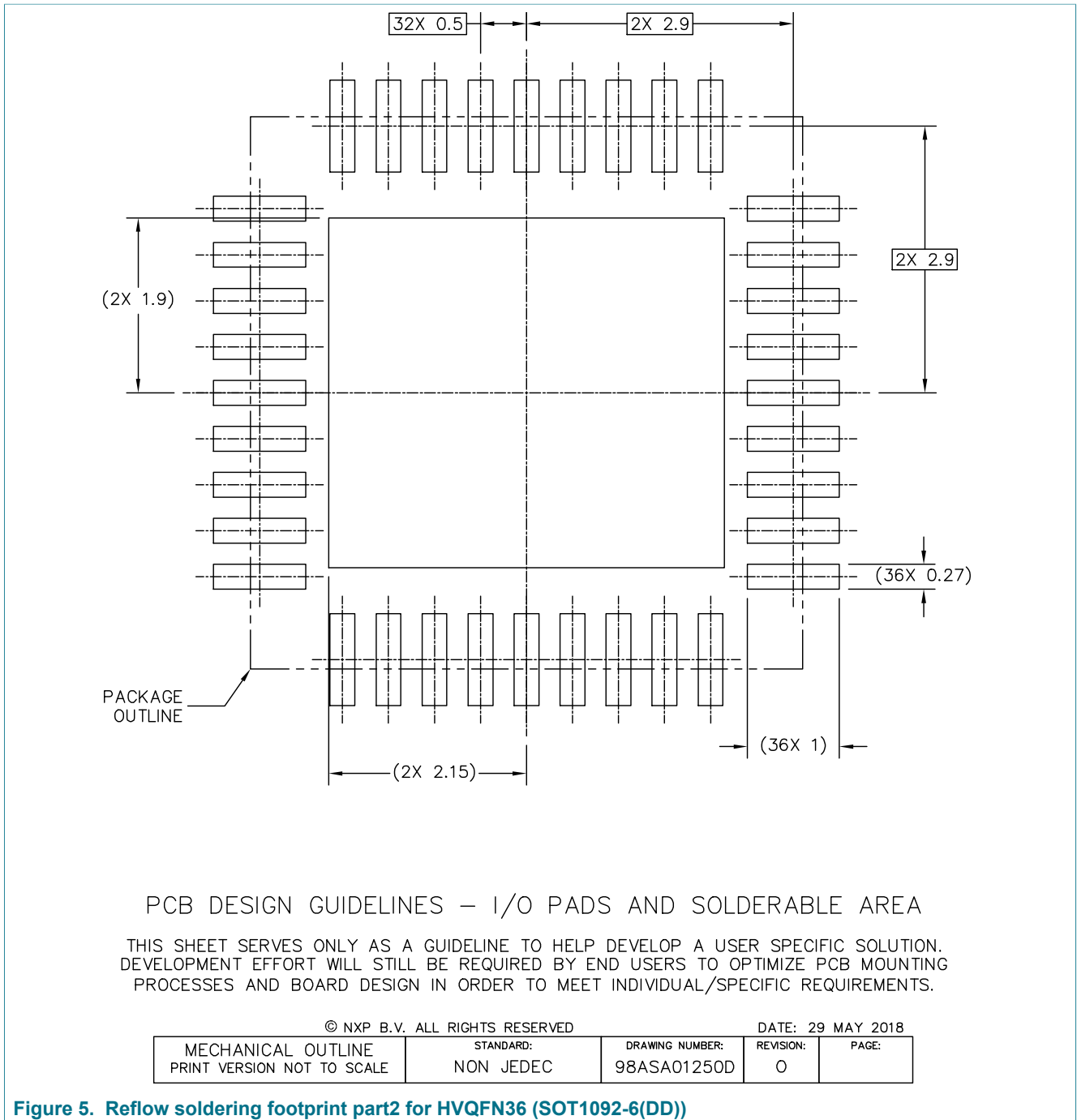


Figure 5. Reflow soldering footprint part2 for HVQFN36 (SOT1092-6(DD))

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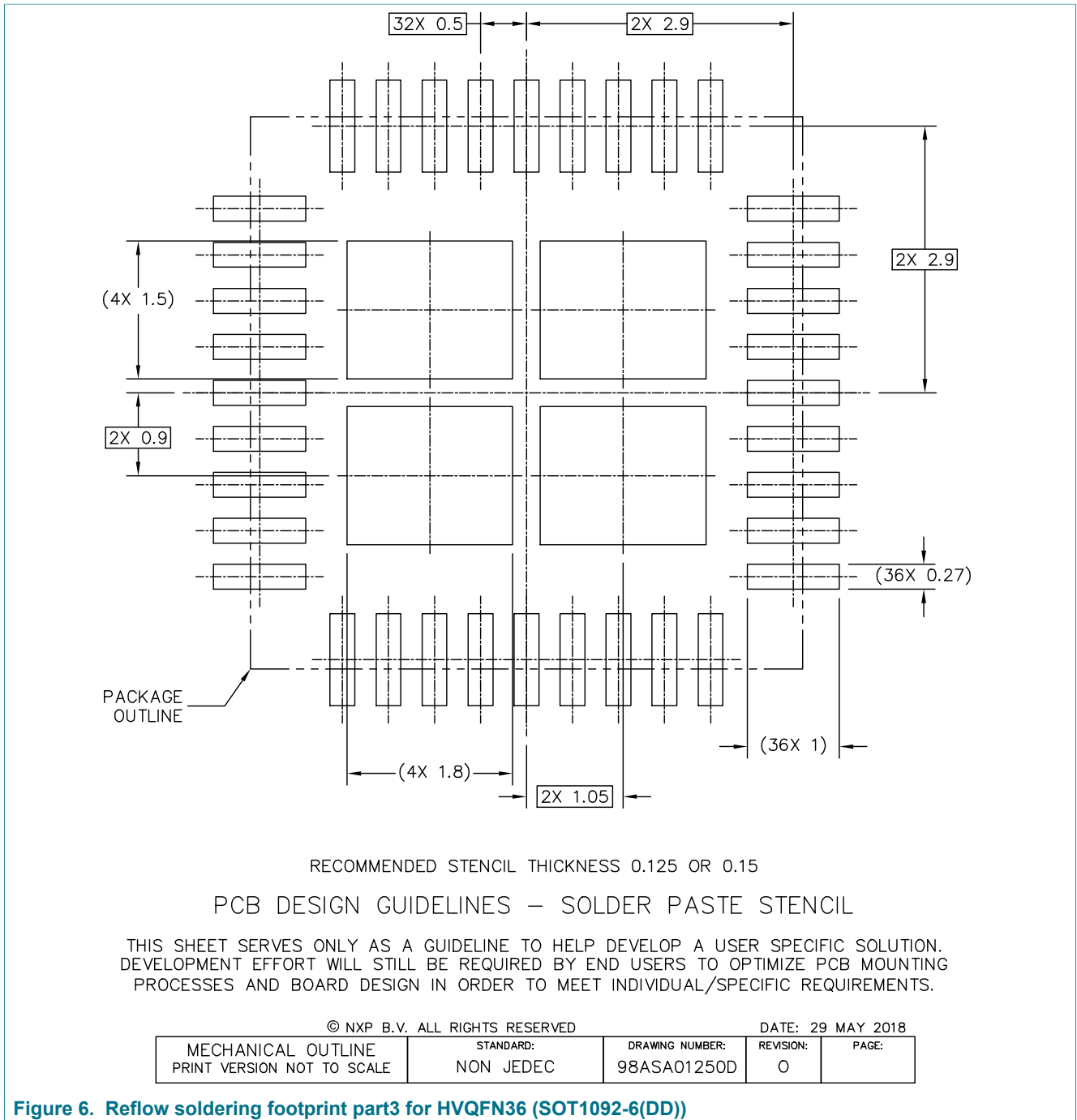


Figure 6. Reflow soldering footprint part3 for HVQFN36 (SOT1092-6(DD))

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4 Legal information

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